

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base		-	-	0.43	K/W
	Cth ₁	2.727E-04 F		Ą	t:	
	Cth ₂	1.961E-03 F		_ 	tj	
	Cth ₃	1.472E-03 F			<u></u>	
	Cth ₄	5.515E-03 F				
	Cth ₅	1.889E-02 F		L	, ,	
	Cth ₆	3.370E-02 F				
	Cth ₇	7.373E-01 F		Г	$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$	
	Cth ₈	2.812E+02 F			$\int Rth_2 = Cth_2$	2
	Rth₁	3.269Ε-04 Ω				
	Rth ₂	6.428E-04 Ω		г	$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$	
	Rth ₃	7.505E-03 Ω			Rth3 🛨 Cth3	5
	Rth ₄	1.817E-02 Ω		L L	╧╺	
	Rth₅	6.176E-02 Ω				
	Rth ₆	2.678E-01 Ω				I
	Rth ₇	7.287E-02 Ω				•
	Rth ₈	6.467E-04 Ω	((Р)		
			·	\checkmark ,	$\neg \neg \neg$	
					Rth5 + Cth5	5
				L	╧╺	
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					Rth7 🚔 Cth7	,
					ᢆᡶ᠊ᢩ	
					_	
Part:	BUK761R5-40E					
)oto:	1/5/0040				$\int Rth_8 \stackrel{\bullet}{=} Cth_8$	5
Date: Nodel Rth	1/5/2013 0.43 K/W					
	0.43 K/W			└── ↑	tamb	
				\diamond	t _{amb} 001aal768	2
					001221/00	•

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